

The aluminium radicle replies copper plate performance table

Performance beacon

Item	Test a condition	AL-01-P Specification	AL-01-A Specification	AL-01-B Specification	AL-01-L Specification	Unit
Thermal conductivity	A	0.6-0.8	1.5	2.0	3.0	W/m.K
Thermal re - sistance		≤ 0.78	≤0.64	≤0.45	≤0.2	°C/W
Solder resistance	288deg.c	120	120	120	120	Sec.
Peel strength normal status	A Thermal stress post	1.4 1.4	1.5 1.5	1.5 1.5	1.3 1.3	N/mm
Volume resistivity normal status	C-96/35/90 E-24/125	10 ⁸ 10 ⁶	10 ⁸ 10 ⁶	10 ⁸ 10 ⁶	10 ⁸ 10 ⁶	MΩ.CM
Surface resistivity normal status	C-96/35/90 E-24/125	10 ⁷ 10 ⁶	10 ⁷ 10 ⁶	10 ⁷ 10 ⁶	10 ⁷ 10 ⁶	MΩ
Dielectric constant	C-96/35/90	4.2	4.9	4.9	4.9	1MH2
Dissipation Factor	C-96/35/90	≤0.02	≤0.02	≤0.02	≤0.02	1MH2
Water absorption		0.1	0.1	0.1	0.1	%
BreakdownVoltage	D-48/50+D-0.5/23	3	3	3	3	KV
Insulationstrength	A	30	30	50	30	KV/mm
Raise camber	A	0.5	0.5	0.5	0.5	%
Flameability	UL94	V-0	V-0	V-0	V-0	
CTI	IEC60112	600	600	600	600	V
TG		158	130	130	130	°C

Product thickness mm	The actinium screen is thick: 1 oz ~ 15 oz, The aluminium board is thick: 0.6 ~ 5.0 mm (Tolerance range ±0.10mm)	
Product specification mm	500×600	500×1200

- The power is hybrid IC(HIC)
- Voice frequency equipment:input, output amplifier, compensating capacitor, the voice frequency amplifier, preamplifier, power amplifier etc..
- Power supply equipment:series voltage regulation, switch modulator, and DC-AC transducer...etc..
- Telecommunication electron equipment:high frequency amplifier, filter telephone, send a telegram telephone.
- Office automation:the printer driver, big electronic display substrate and thermal print A class.
- Autocar:the igniter, power supply modulator and swap transform machine, power supply controller, become only system etc..
- Calculator:CPU board, soft pan driver, and power supply device...etc..
- Power mold mass:change to flow a machine, solid relay, commutate bridge etc..
- LED light, heat and water expense:big power LED light, LED wall etc..

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Item	Test a condition	Unit	CU-01-P Specification	CU-01-B Specification
Thermal conductivity	A	W/m.K	0.6-0.8	1.98-2.1
Thermal re - sistance		°C/W	≤ 0.78	≤0.45
Solder resistance	288°C	Sec.	120	120
Peel strength normal status	A Thermal stress post	N/mm	1.4 1.4	1.5 1.5
Volume resistivity normal status	C-96/35/90 E-24/125	MΩ.CM	10 ⁸ 10 ⁶	10 ⁸ 10 ⁶
Surface resistivity normal status	C-96/35/90 E-24/125	MΩ	10 ⁷ 10 ⁶	10 ⁷ 10 ⁶
Dielectric constant	C-96/35/90	1MH2	4.2	4.9
Dissipation Factor	C-96/35/90	1MH2	≤0.02	≤0.02
Water absorption		%	0.1	0.1
BreakdownVoltage	D-48/50+D-0.5/23	KV	3	3
Insulationstrength	A	KV/mm	30	30
Raise camber	A	%	0.5	0.5
Flameability	UL94		V-0	V-0
CTI	IEC60112	V	600	480
TG		°C	158	130

Product thickness mm	600*500
Product specification mm	The actinium screen is thick: : H oz ~ 15 oz, The aluminium board is thick: : 0.8 ~ 5.0 mm (Tolerance range ±0.10mm)

- The power is hybrid IC(HIC)
- Voice frequency equipment:input, output amplifier, compensating capacitor, the voice frequency amplifier, preamplifier, power amplifier etc..
- Power supply equipment:series voltage regulation, switch modulator, and DC-AC transducer...etc..
- Telecommunication electron equipment:high frequency amplifier, filter telephone, send a telegram telephone.
- Office automation:the printer driver, big electronic display substrate and thermal print A class.
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